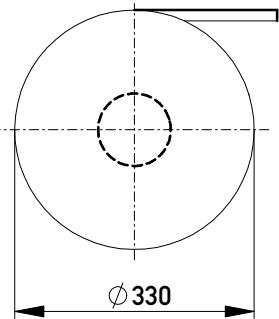
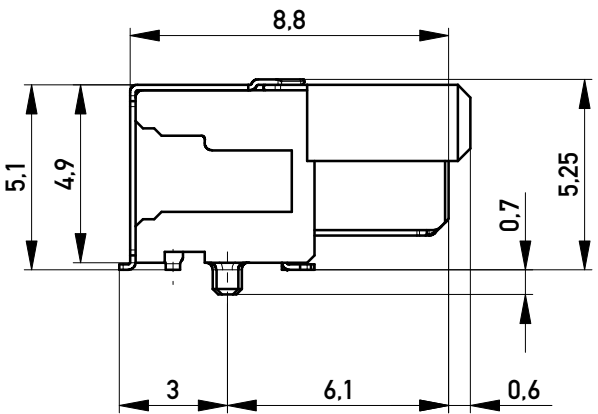
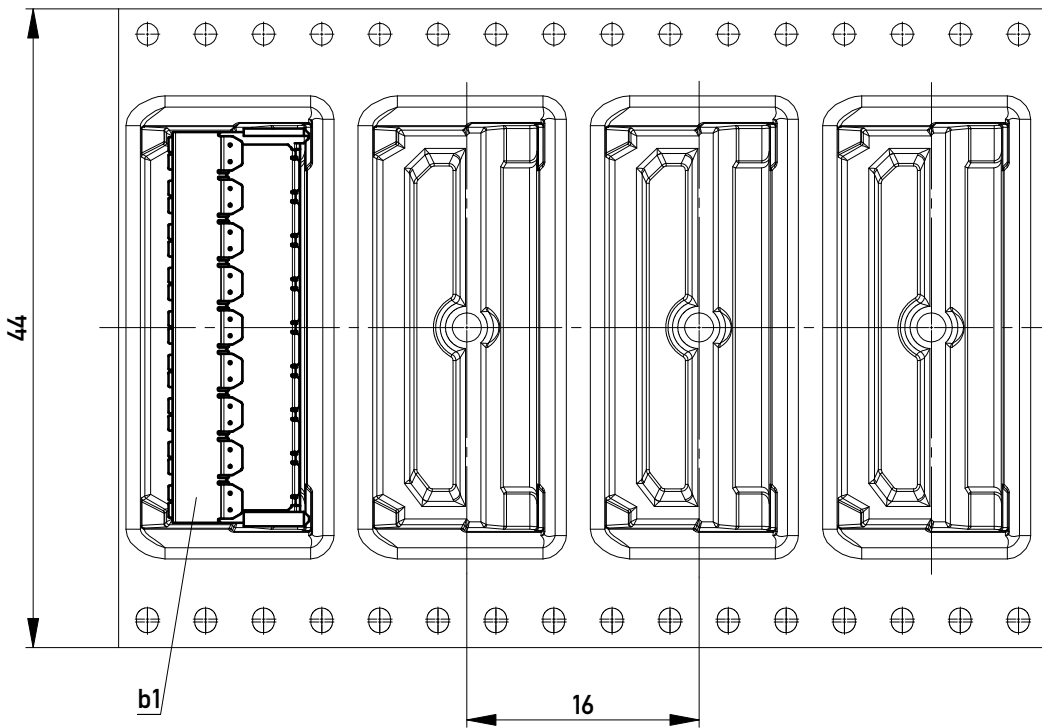


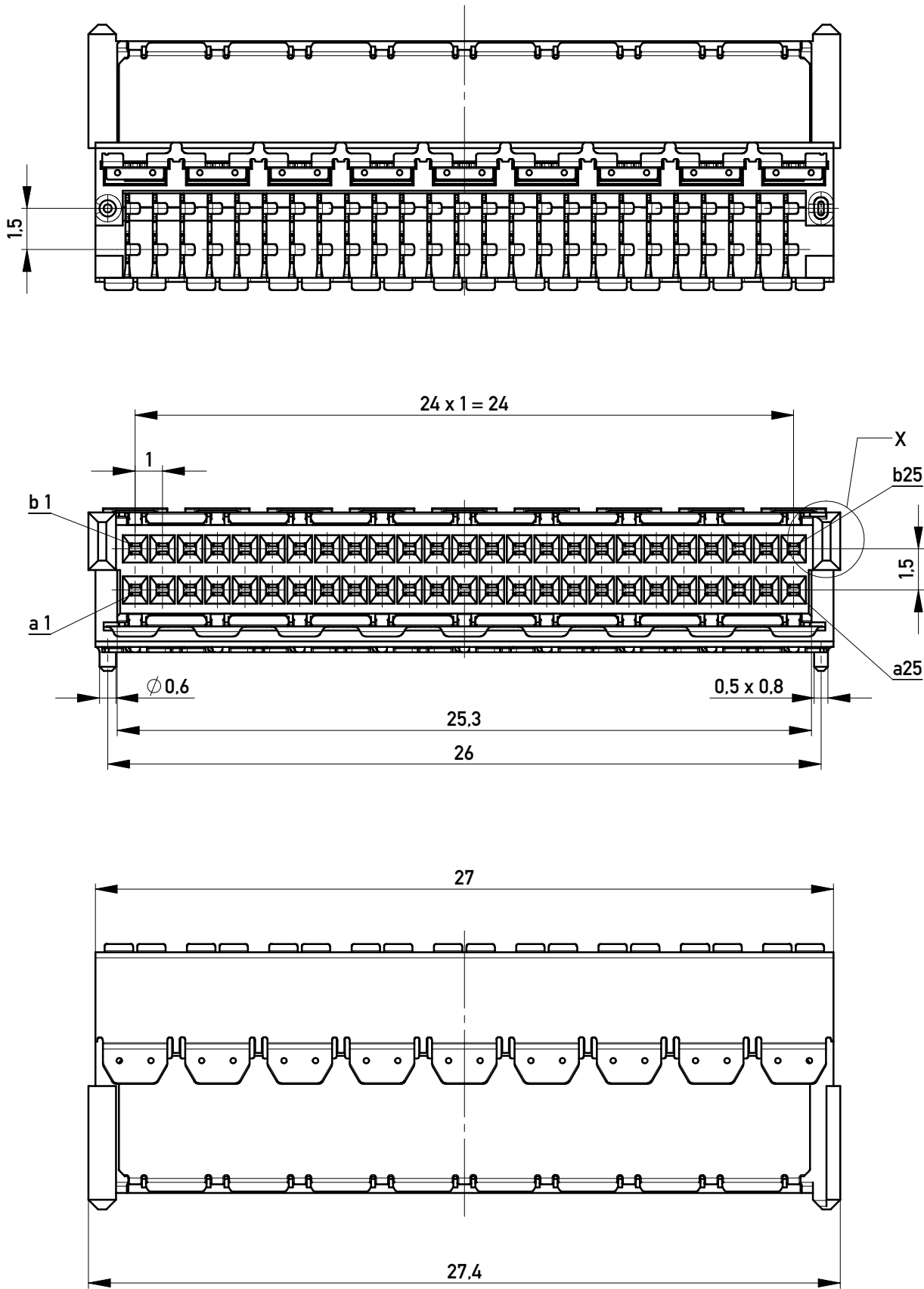
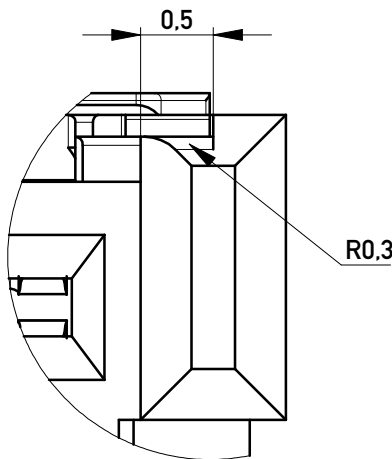
Verpackt im Gurt in Anlehnung an DIN IEC 60286-3
Tape on Reel Packaging according to DIN IEC 60286-3
Verpackungseinheit: 500 Stück
Packaging unit: 500 pcs



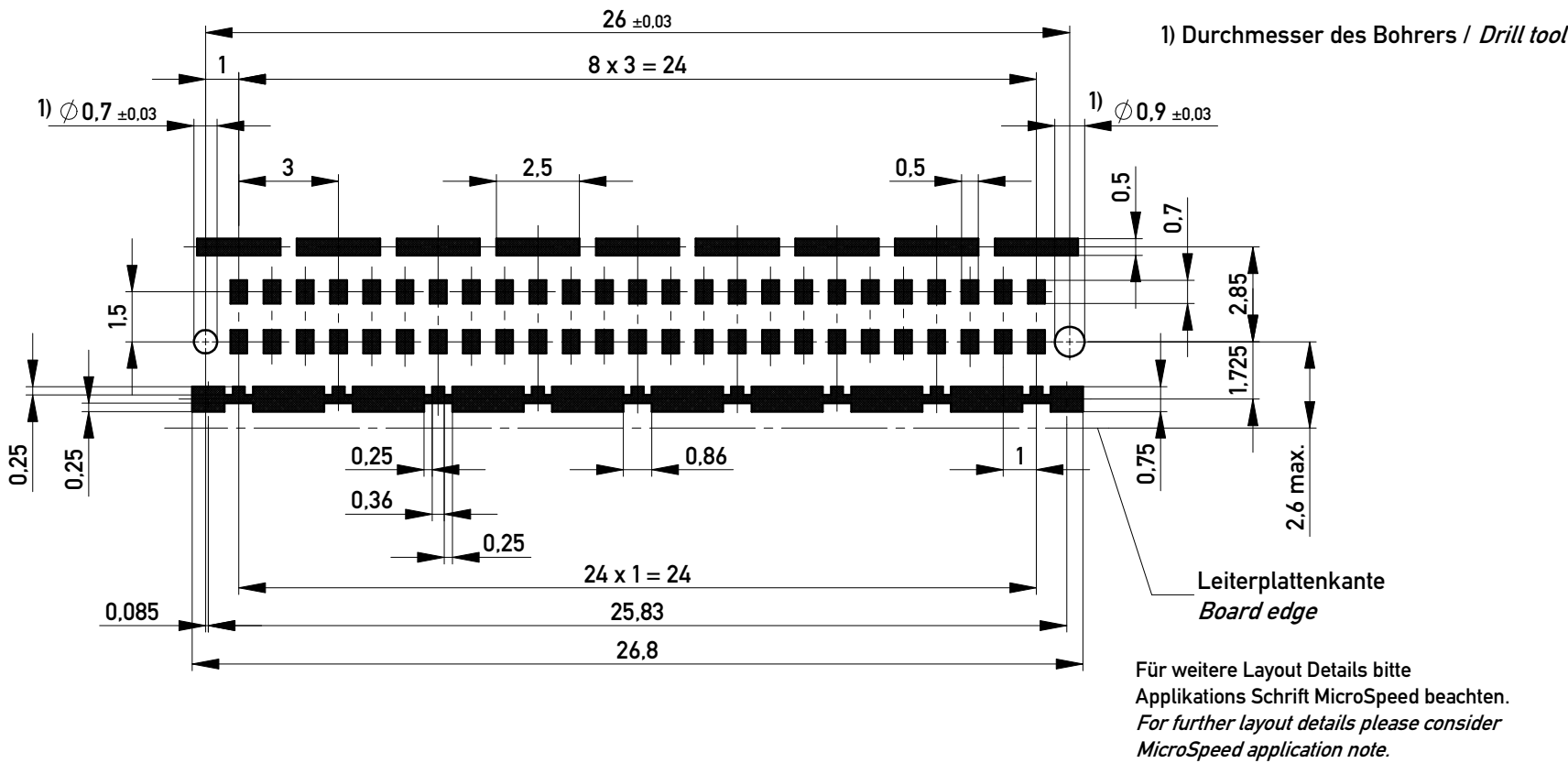
Abspulrichtung - Reel off Direction



Einzelheit X
M 20:1



Leiterplatten-Layout Vorschlag / PCB-Layout Proposal



1) Durchmesser des Bohrers / Drill tool

Leiterplattenkante
Board edge

Für weitere Layout Details bitte
Applikations Schrift MicroSpeed beachten.
For further layout details please consider
MicroSpeed application note.

Anforderungsstufe 1
Performance Level 1

Kontaktbereich vergoldet
Mating Area gold plating

Anschlussbereich verzinkt 4-6 µm
Terminal Area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm
Coplanarity Area of Termination ≤ 0,1 mm

Information:		Tolerances		Scale	5:1
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h		06.09.2016			Federl. 90° 50p. BM SMD EMV
Index		Date	www.ERNI.com		Female 90° 50 c. BM SMD EMV
Class				284310	I
				MSPEED	A2